Technical Data Sheet
3mm Infrared LED, T-1

H Y 3 2 0 R

Features

- High reliability
- High radiant intensity
- Peak wavelength λp=940nm
- 2.54mm Lead spacing
- Low forward voltage
- Pb free
- The product itself will remain within RoHS compliant version.

Descriptions

- HYGD's infrared emitting diode(H Y 3 2 0 R) is a high intensity diode , molded in a water clear plastic package.
- The device is spectrally matched with phototransistor , photodiode and infrared receiver module.

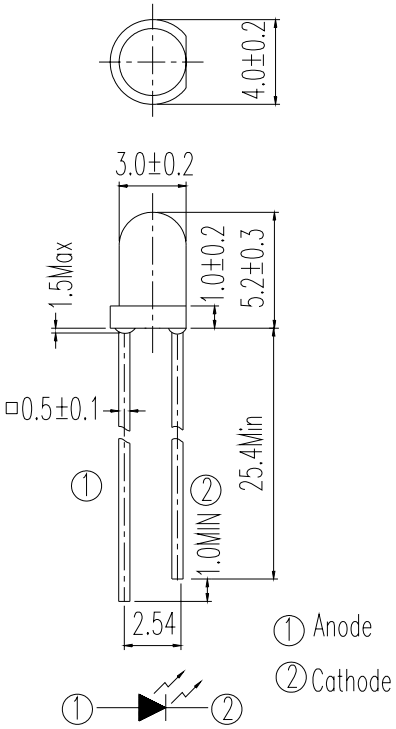
Applications

- Free air transmission system
- Infrared remote control units with high power requirement
- Smoke detector
- Infrared applied system

Device Selection Guide

LED Part No.	Chip Material	Lens Color
HIR	GaAlAs	Water clear

Package Dimensions



Notes: 1.All dimensions are in millimeters
2.Tolerances unless dimensions ±0.25mm

Absolute Maximum Ratings (Ta=25℃)

Parameter	Symbol	Rating	Units
Continuous Forward Current	I_F	100	mA
Peak Forward Current	I_{FP}	1.0	A
Reverse Voltage	V_R	5	V
Operating Temperature	T_{opr}	-40 ~ +85	℃
Storage Temperature	T_{stg}	-40 ~ +85	℃
Soldering Temperature	T_{sol}	260	℃
Power Dissipation at(or below) 25℃ Free Air Temperature	P_d	150	mW

Notes: *1:I_{FP} Conditions--Pulse Width≦100 μs and Duty≦1%.
*2:Soldering time≦5 seconds.

Electro-Optical Characteristics (Ta=25℃)

Parameter	Symbol	Condition	Min.	Typ.	Max.	Units
Radiant Intensity	Ee	I_F=20mA	4.0	8.9	--	mW/sr
		I_F=100mA Pulse Width≦100 μs ,Duty≦1%	--	30	--	
		I_F=1A Pulse Width≦100 μs ,Duty≦1%.	--	380	--	
Peak Wavelength	λp	I_F=20mA	--	850	--	nm
Spectral Bandwidth	Δλ	I_F=20mA	--	45	--	nm
Forward Voltage	V_F	I_F=20mA		1.45	1.65	V
		I_F=100mA Pulse Width≦100 μs ,Duty≦1%	--	1.80	2.40	
		I_F=1A Pulse Width≦100 μs ,Duty≦1%.	--	4.10	5.25	
Reverse Current	I_R	V_R=5V	--	--	10	μA
View Angle	2θ1/2	I_F=20mA	--	40	--	deg

Rank

Condition：I_F=20mA

Unit：mW/sr

Bin Number	K	L	M	N
Min	4.0	5.6	7.8	11.0
Max	6.4	8.9	12.5	17.6

Typical Electro-Optical Characteristics Curves

Fig.1 Forward Current vs. Ambient Temperature

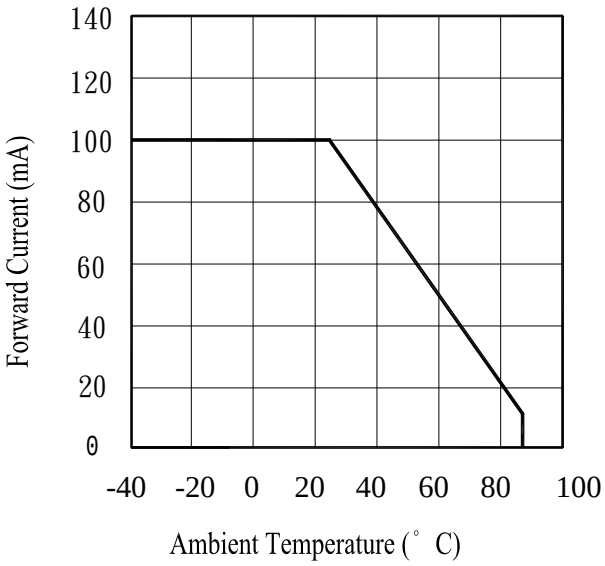


Fig.2 Spectral Distribution

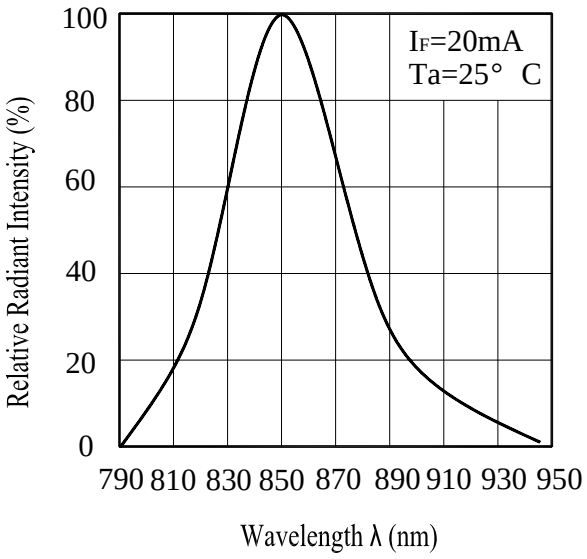


Fig.3 Peak Emission Wavelength Ambient Temperature

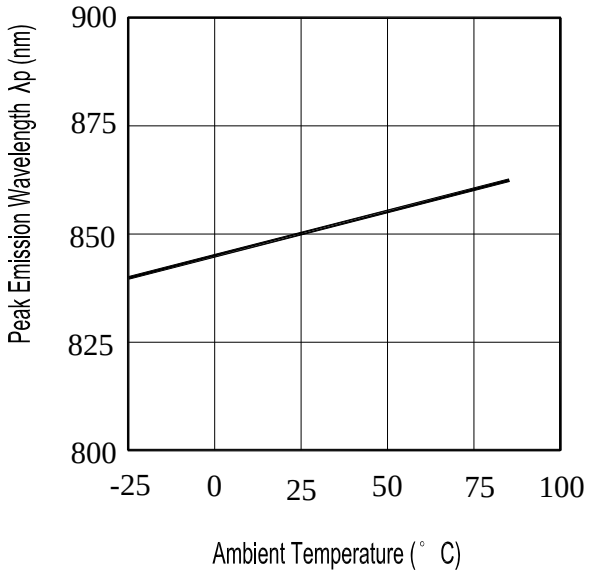
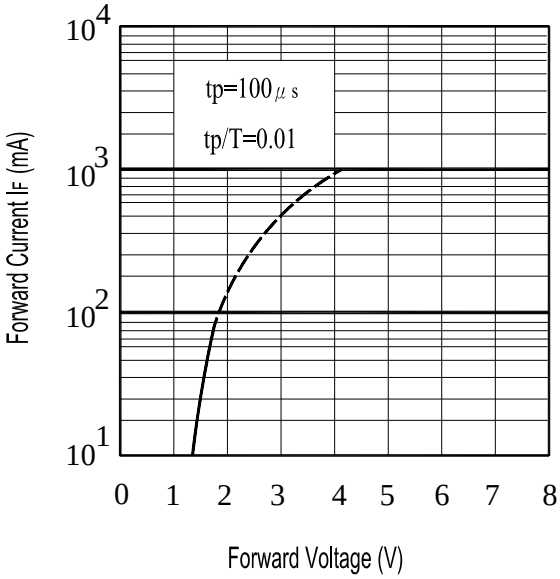


Fig.4 Forward Current vs. Forward Voltage



Typical Electro-Optical Characteristics Curves

Fig.5 Relative Intensity vs. Forward Current

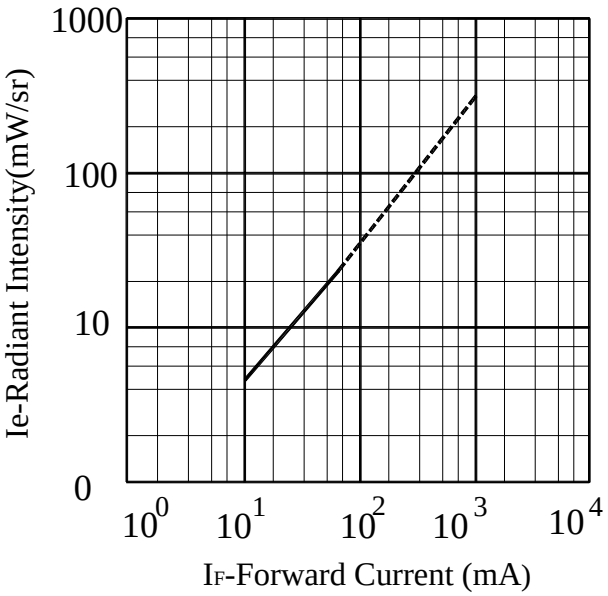


Fig.6 Relative Radiant Intensity vs. Angular Displacement

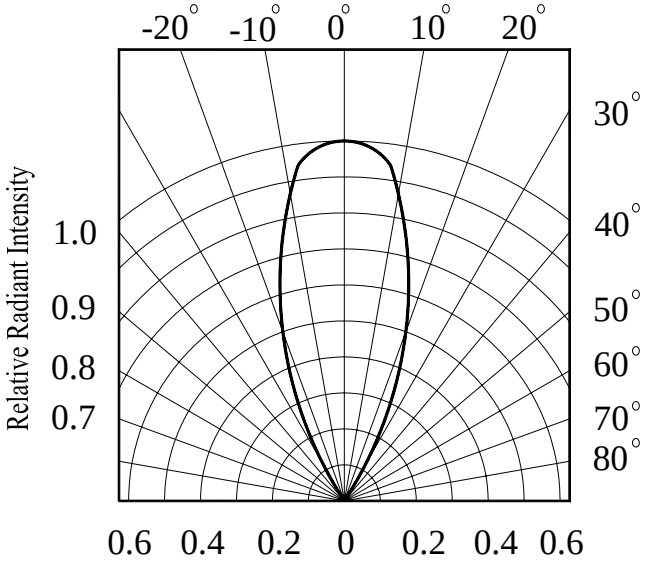


Fig.7 Relative Intensity vs. Ambient Temperature(°C)

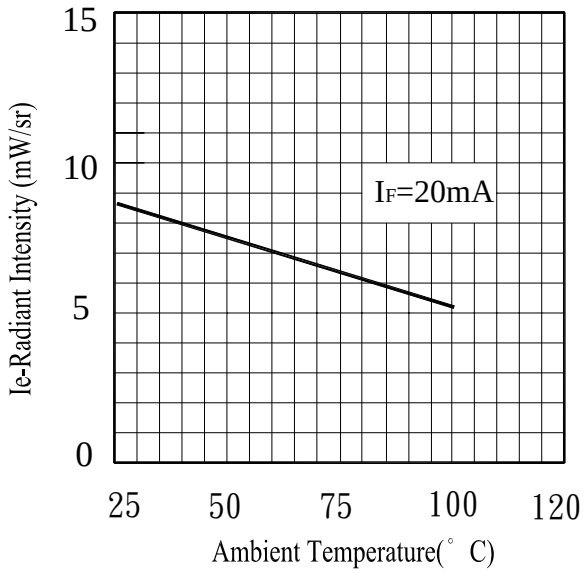
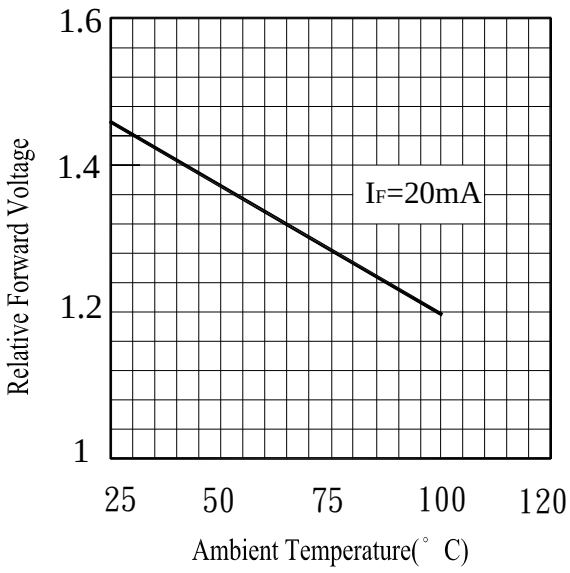


Fig.8 Forward Voltage vs. Ambient Temperature(°C)



Reliability Test Item And Condition

The reliability of products shall be satisfied with items listed below.

Confidence level：90%

LTPD：10%

NO.	Item	Test Conditions	Test Hours/ Cycles	Sample Sizes	Failure Judgement Criteria	Ac/Re
1	Solder Heat	TEMP.：260℃±5℃	10secs	22pcs	$I_R \geqq U \times 2$ $Ee \leqq L \times 0.8$ $V_F \geqq U \times 1.2$ U：Upper Specification Limit L：Lower Specification Limit	0/1
2	Temperature Cycle	H：+100℃ 15mins 5mins L：-40℃ 15mins	300Cycles	22pcs		0/1
3	Thermal Shock	H：+100℃ 5mins 10secs L：-10℃ 5mins	300Cycles	22pcs		0/1
4	High Temperature Storage	TEMP.：+100℃	1000hrs	22pcs		0/1
5	Low Temperature Storage	TEMP.：-40℃	1000hrs	22pcs		0/1
6	DC Operating Life	I_F=20mA	1000hrs	22pcs		0/1
7	High Temperature/ High Humidity	85℃ / 85% R.H	1000hrs	22pcs		0/1